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Application ID: 10680783



Title of Invention:  
HIGH-PRESSURE PROCESSING  
CHAMBER FOR A  
SEMICONDUCTOR WAFER

First Named Inventor: William Jones

Domestic/Foreign Application: Domestic Application

Filing Date: 2003-10-06

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Submission Type:  
Information Disclosure  
Statement

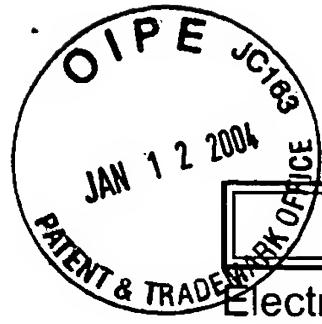
Filing Type:

Confirmation number: 5859

Attorney Docket Number: NONE

Total Fees Authorized:

Digital Certificate Holder: cn=Thomas B. Haverstock,ou=Registered Attorneys,ou=Patent and Trademark Office,ou=Department of Commerce,o=U.S. Government,c=US  
Certificate Message Digest: 61d5c9b8f94c7d7c69e4b26fab22594eb5f0f953

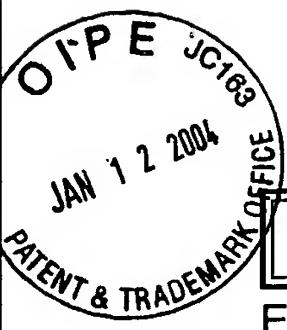


## TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER	
Application Number:	10/680783	
Date:	2003-10-06	
First Named Applicant:	William Dale Jones	
Confirmation Number:	5859	
Attorney Docket Number:		
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Submitted by:	Elec. Sign.	Sign. Capacity
Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney
Documents being submitted us-ids	Files SSI04001C-usidst.xml us-ids.dtd us-ids.xsl	
Comments		



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18  
Stylesheet Version v18.0

Title of Invention	HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER						
Application Number:	10/680783 						
Confirmation Number:	5859						
First Named Applicant:	William Jones						
Attorney Docket Number:							
Search string:	( 5882165 or 5888050 or 5898727 or 5900107 or 5904737 or 5928389 or 5932100 or 5934856 or 5934991 or 5979306 or 5980648 or 5981399 or 5989342 or 6005226 or 6017820 or 6029371 or 6035871 or 6037277 or 6053348 or 6056008 or 6067728 or 6077053 or 6077321 or 6082150 or 6085935 or 6097015 or 6128830 or 6145519 or 6159295 or 6164297 or 6186722 or 6203582 or 6216364 or 6228563 or 6235634 or 6239038 or 6241825 or 6251250 or 6244121 or 6277753 or 6286231 or 6305677 or 6334266 or 6344174 or 6388317 or 6389677 or 6418956 or 6436824 or 6454945 or 6464790 ).pn.						
<b>US Patent Documents</b>							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5882165	1999-03-16	Maydan et al.			
	2	5888050	1999-03-30	Fitzgerald et al.			
	3	5898727	1999-04-27	Fujikawa et al.			
	4	5900107	1999-05-04	Murphy et al.			
	5	5904737	1999-05-18	Preston et al.			
	6	5928389	1999-07-27	Jevtic			
	7	5932100	1999-08-03	Yager et al.			
	8	5934856	1999-08-10	Asakawa et al.			
	9	5934991	1999-08-10	Rush			
	10	5979306	1999-11-09	Fujikawa et al.			

	11	5980648	1999-11-09	Adler	
	12	5981399	1999-11-09	Kawamura et al.	
	13	5989342	1999-11-23	Ikeda et al.	
	14	6005226	1999-12-21	Aschner et al.	
	15	6017820	2000-01-25	Ting et al.	
	16	6029371	2000-02-29	Kamikawa et al.	
	17	6035871	2000-03-14	Eui-Yeol	
	18	6037277	2000-03-14	Masakara et al.	
	19	6053348	2000-04-25	Morch	
	20	6056008	2000-05-02	Adams et al.	
	21	6067728	2000-05-30	Farmer et al.	
	22	6077053	2000-06-20	Fujikawa et al.	
	23	6077321	2000-06-20	Adachi et al.	
	24	6082150	2000-07-04	Stucker	
	25	6085935	2000-07-11	Malchow et al.	
	26	6097015	2000-08-01	McCullough et al.	
	27	6128830	2000-10-10	Bettcher et al.	
	28	6145519	2000-11-14	Konishi et al.	
	29	6159295	2000-12-12	Maskara et al.	
	30	6164297	2000-12-26	Kamikawa	
	31	6186722	2001-02-13	Shirai	B1
	32	6203582	2001-03-20	Berner et al.	B1
	33	6216364	2001-04-17	Tanaka et al.	B1
	34	6228563	2001-05-08	Starov et al.	B1
	35	6235634	2001-05-22	White et al.	B1
	36	6239038	2001-05-29	Wen	B1
	37	6241825	2001-06-05	Wytman	B1
	38	6251250	2001-06-26	Keigler	B1
	39	6244121	2001-06-12	Hunter	B1
	40	6277753	2001-08-21	Mullee et al.	B1
	41	6286231	2001-09-11	Bergman et al.	B1
	42	6305677	2001-10-23	Lenz	B1
	43	6334266	2002-01-01	Moritz et al.	B1
	44	6344174	2002-02-05	Miller et al.	B1
	45	6388317	2002-05-14	Reese	B1
	46	6389677	2002-05-21	Lenz	B1

	47	6418956	2002-07-16	Bloom	B1
	48	6436824	2002-08-20	Chooi et al.	B1
	49	6454945	2002-09-24	Weigl et al.	B1
	50	6464790	2002-10-15	Shertinsky et al.	B1

## Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal. The current electronic filing contains part 3 out of a total of 4 electronic filings.

## Signature

Examiner Name	Date